

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IAUS240N08S5N019	**Issued**	16. May 2021
MA#	MA005344622		
Package	PG-HSOG-8-1	**Weight***	705.31 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.611	0.65	0.65	6538	6538
leadframe	inorganic material	phosphorus	7723-14-0	0.040	0.01		57	
	non noble metal	iron	7439-89-6	0.134	0.02		191	
	non noble metal	copper	7440-50-8	134.219	19.03	19.06	190298	190546
wire	non noble metal	aluminium	7429-90-5	15.908	2.26	2.26	22554	22554
encapsulation	inorganic material	zincoxide	1314-13-2	2.619	0.37		3713	
	miscellaneous	miscellaneous	-	10.474	1.49		14851	
	plastics	epoxy resin	-	39.278	5.57		55690	
	inorganic material	silicondioxide	60676-86-0	209.484	29.70	37.13	297011	371265
leadfinish	non noble metal	tin	7440-31-5	8.309	1.18	1.18	11781	11781
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.220	0.03	0.03	311	312
solder	non noble metal	tin	7440-31-5	0.079	0.01		112	
	noble metal	silver	7440-22-4	0.099	0.01		140	
	non noble metal	lead	7439-92-1	3.770	0.53	0.55	5345	5597
heatspreader	inorganic material	phosphorus	7723-14-0	0.083	0.01		117	
	non noble metal	iron	7439-89-6	0.276	0.04		391	
	non noble metal	copper	7440-50-8	275.705	39.09	39.14	390899	391407
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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